

Transfer Molding System

Model YPM1250-EPQ



Transfer molding system for 2.5D/3DIC/Chiplet products

Transfer molding system for 2.5D/3DIC/Chiplet system

Product information



English

- Large press capable of handling individual substrate sizes up to 150 mm (6 inch).
- Compatible with boat carriers for individual substrate handling.
- Edge gate design prevents resin leakage such as side rail flashing.
- Large flow cavity and R.F.C.P. enable MUF molding of large chips which are difficult to fill.
- Double plunger supports necessary resin amount for large-area.
- Modular concept to adapt to different production quantities.



SPECIFICATION

Items		Unit	Description			
Model		—	YPM1250-EPQ			
Workpiece type		—	Substrate			
Workpiece size		mm	□60—□150/100×300 (Max.)			
Boat carrier size	Length	mm	310—390			
	Width	mm	160—200			
Molding compound	Diameter	mm	φ 14, 16, 18, 20			
	Length	mm	14.3—35.0			
Machine time		sec	Approximately 108			
External dimensions	Number of press modules	module	1	2	3	4
	Width	mm	5,240	6,240	7,240	8,240
	Depth	mm	2,000	2,000	2,000	2,000
	Height	mm	2,685	2,685	2,685	2,685
Weight		ton	15.0	23.0	31.0	40.0
Number of workpieces per cycle	Workpiece size □60—□90	workpiece	6			
	Workpiece size □85—□150	workpiece	4			
Input magazine setting space		mm	870			
Output magazine setting space (Slit magazine type)		mm	870			
Clamp capacity		kN/(tf)	294.0—2,450.0/30.0—250.0			
Transfer capacity		kN/(tf)	9.8—98.0/1.0—10.0 (2 step pressure setting)			
Conversion method to different product type		—	"Conversion kit" method			
Mountable mold		—	Dedicated mold of YPM1250-EPQ			
Release film width		mm	100—530			

- The figures shown above are based on standard machine specifications.
- The above specification are subject to change without prior notice.
- For special requirements, please consult your local TOWA representative.




Headquarters

5 Kamichoshi-cho, Kamitoba, Minami-ku, Kyoto-shi,
Kyoto 601-8105 Japan

Contact Us



TOWA (our company's house mark),  are trademarks or registered trademarks of TOWA Corporation.
R.F.C.P. is a trademark and registered trademark of TOWA Corporation
in the United States and other countries.

Overseas Sales Contacts

China

TOWA (Shanghai) Co., Ltd.

Taiwan

TOWA Taiwan Co., Ltd.

Korea

TOWA Korea Co., Ltd.

Singapore

TOWA Asia-Pacific Pte. Ltd.

Malaysia

TOWA Malaysia Sales &
Services Sdn. Bhd.

Thailand

TOWA THAI COMPANY LIMITED

Philippines

TOWA Semiconductor Equipment
Philippines Corp.

India

TOWA SEMICONDUCTOR INDIA
PRIVATE LIMITED

Germany

TOWA Europe GmbH

Netherlands

TOWA Europe B.V.

the United States

TOWA USA Corporation

20250401-004-HQ